

## **Description**

The DMTH43M8LPS-13 uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

# D D D S S S S S S Pin 1

#### DFN5X6-8L

### **General Features**

 $V_{DS} = 40V I_{D} = 130A$ 

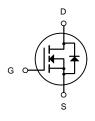
 $R_{DS(ON)} < 3.5m\Omega$  Vgs=10V

## **Application**

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

## **Package Marking and Ordering Information**

| Product ID     | Pack      | Brand      | Qty(PCS) |
|----------------|-----------|------------|----------|
| DMTH43M8LPS-13 | DFN5X6-8L | HXY MOSFET | 5000     |

## Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

| Symbol                                | Parameter  | Rating     | Units |
|---------------------------------------|--|------------|-------|
| V <sub>DS</sub>                       | Drain-Source Voltage   | 40         | V     |
| Vgs                                   | Gate-Source Voltage  | ±20        | V     |
| I <sub>D</sub> @T <sub>C</sub> =25°C  | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | 130        | А     |
| I <sub>D</sub> @T <sub>C</sub> =100°C | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | 65         | А     |
| Ірм                                   | Pulsed Drain Current <sup>2</sup>                            | 400        | А     |
| EAS                                   | Single Pulse Avalanche Energy <sup>3</sup>                   | 150        | mJ    |
| Тѕтс                                  | Storage Temperature Range                                    | -55 to 175 | °C    |
| TJ                                    | Operating Junction Temperature Range                         | -55 to 175 | °C    |

## N-Channel Enhancement Mode MOSFET

# Electrical Characteristics (T<sub>C</sub>=25 ℃ unless otherwise noted)

| Parameter                          | Symbol              | Condition  | Min | Тур  | Max  | Unit |  |
|------------------------------------|---------------------|--|-----|------|------|------|--|
| Off Characteristics                | ·                   |  |     |      |      |      |  |
| Drain-Source Breakdown Voltage     | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V I <sub>D</sub> =250μA 40                         |     | -    | -    | V    |  |
| Zero Gate Voltage Drain Current    | I <sub>DSS</sub>    | V <sub>DS</sub> =40V,V <sub>GS</sub> =0V                             | -   | -    | 1    | μA   |  |
| Gate-Body Leakage Current          | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V                            | -   | -    | ±100 | nA   |  |
| On Characteristics (Note 3)        | ·                   |  |     |      |      |      |  |
| Gate Threshold Voltage             | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA              | 1   | 1.6  | 2.5  | V    |  |
| Drain-Source On-State Resistance   | R <sub>DS(ON)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =30A                            | -   | 2.8  | 3.5  | mΩ   |  |
| Forward Transconductance           | <b>g</b> Fs         | V <sub>DS</sub> =5V,I <sub>D</sub> =20A                              | 50  | -    | -    | S    |  |
| Dynamic Characteristics (Note4)    |                     |  | •   |      |      |      |  |
| Input Capacitance                  | C <sub>Iss</sub>    | V 05VV 0V  | -   | 5584 | -    | PF   |  |
| Output Capacitance                 | C <sub>oss</sub>    | $V_{DS}$ =25V, $V_{GS}$ =0V,<br>F=1.0MHz                             | -   | 410  | -    | PF   |  |
| Reverse Transfer Capacitance       | C <sub>rss</sub>    | F=1.0IVIHZ   | -   | 338  | -    | PF   |  |
| Switching Characteristics (Note 4) |                     |  |     |      |      |      |  |
| Turn-on Delay Time                 | t <sub>d(on)</sub>  |  | -   | 11   | -    | nS   |  |
| Turn-on Rise Time                  | t <sub>r</sub>      | $V_{DD}=20V,I_{D}=20A,R=1\Omega$                                     | -   | 15   | -    | nS   |  |
| Turn-Off Delay Time                | t <sub>d(off)</sub> | $V_{GS}$ =10V, $R_{GEN}$ =3 $\Omega$                                 | -   | 38   | -    | nS   |  |
| Turn-Off Fall Time                 | t <sub>f</sub>      |  | -   | 14   | -    | nS   |  |
| Total Gate Charge                  | Qg                  | \/ -20\/L-20A  | -   | 64   | -    | nC   |  |
| Gate-Source Charge                 | Q <sub>gs</sub>     | $V_{DS}=30V,I_{D}=30A,$<br>$V_{GS}=10V$                              | -   | 12.4 | -    | nC   |  |
| Gate-Drain Charge                  | $Q_{\mathrm{gd}}$   | V <sub>GS</sub> =10V   | -   | 14   | -    | nC   |  |
| Drain-Source Diode Characteristics |                     |  | •   |      |      |      |  |
| Diode Forward Voltage (Note 3)     | V <sub>SD</sub>     | V <sub>GS</sub> =0V,I <sub>S</sub> =30A                              | -   | -    | 1.2  | V    |  |
| Diode Forward Current (Note 2)     | Is                  |  | -   | -    | 130  | Α    |  |
| Reverse Recovery Time              | t <sub>rr</sub>     | TJ = 25°C, IF =30A   | -   | 22   |      | nS   |  |
| Reverse Recovery Charge            | Qrr                 | di/dt = 100A/µs <sup>(Note3)</sup>                                   | -   | 11   |      | nC   |  |
| Forward Turn-On Time               | t <sub>on</sub>     | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD) |     |      |      |      |  |

#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- **4.** Guaranteed by design, not subject to production
- **5.** E<sub>AS</sub> condition: Tj=25  $^{\circ}$ C,V<sub>DD</sub>=30V,V<sub>G</sub>=10V,L=0.5mH,Rg=25 $\Omega$



# **Typical Characteristics**

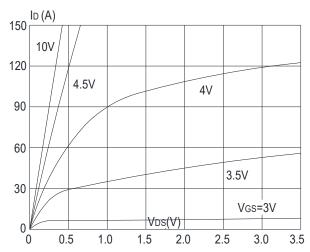
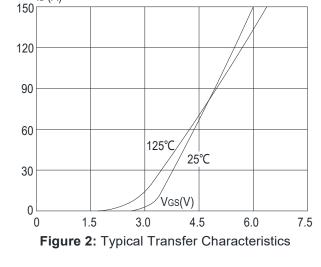


Figure1: Output Characteristics



ID (A)

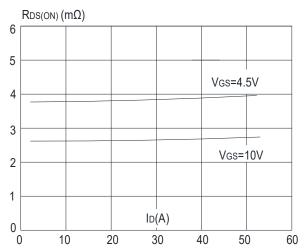


Figure 3:On-resistance vs. Drain Current

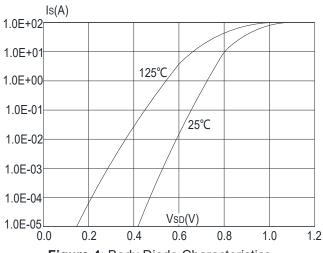


Figure 4: Body Diode Characteristics

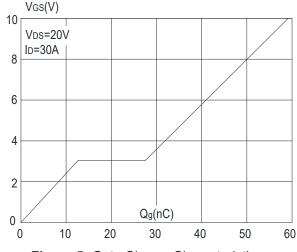


Figure 5: Gate Charge Characteristics

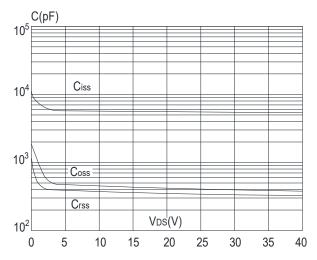
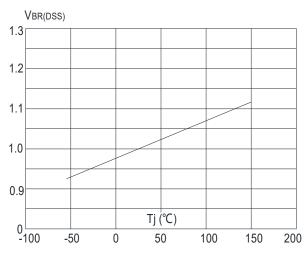


Figure 6: Capacitance Characteristics



**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature

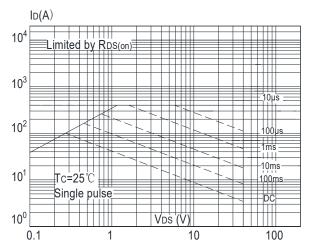
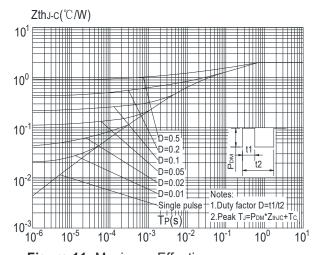
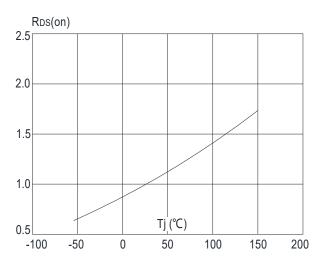


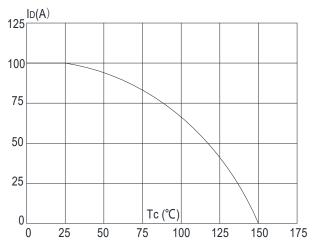
Figure 9: Maximum Safe Operating Area



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



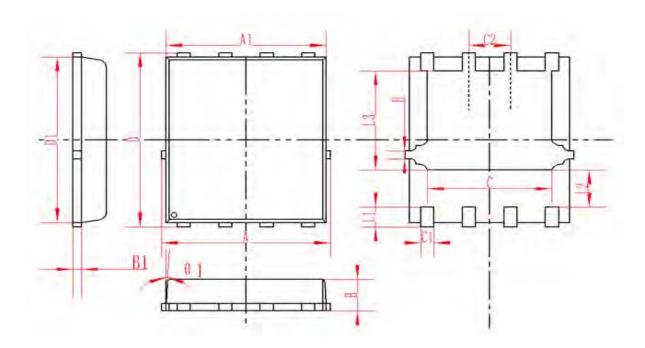
**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



# **DFN5X6-8L Package Information**



| SYMBOL | MM    |          | INCH  |       |          |       |
|--------|-------|----------|-------|-------|----------|-------|
|        | MIN   | NOM      | MAX   | MIN   | NOM      | MAX   |
| А      | 4.95  | 5        | 5.05  | 0.195 | 0.197    | 0.199 |
| A1     | 4.82  | 4.9      | 4.98  | 0.190 | 0.193    | 0.196 |
| D      | 5.98  | 6        | 6.02  | 0.235 | 0.236    | 0.237 |
| D1     | 5.67  | 5.75     | 5.83  | 0.223 | 0.226    | 0.230 |
| В      | 0.9   | 0.95     | 1     | 0.035 | 0.037    | 0.039 |
| B1     |       | 0.254REF |       |       | 0.010REF |       |
| С      | 3.95  | 4        | 4.05  | 0.156 | 0.157    | 0.159 |
| C1     | 0.35  | 0.4      | 0.45  | 0.014 | 0.016    | 0.018 |
| C2     |       | 1.27TYP  |       |       | 0.5TYP   |       |
| θ1     | 8°    | 10°      | 12°   | 8°    | 10°      | 12°   |
| L1     | 0.63  | 0.64     | 0.65  | 0.025 | 0.025    | 0.026 |
| L2     | 1.2   | 1.3      | 1.4   | 0.047 | 0.051    | 0.055 |
| L3     | 3.415 | 3.42     | 3.425 | 0.134 | 0.135    | 0.135 |
| Н      | 0.24  | 0.25     | 0.26  | 0.009 | 0.010    | 0.010 |



#### N-Channel Enhancement Mode MOSFET

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